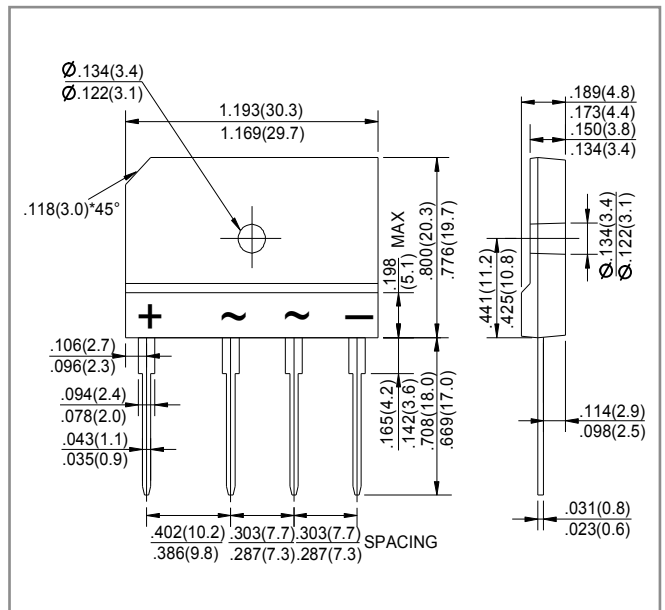


Volatge Rangs - 50 to 1000 Volts
Forward Current - 6.0 Amperes

Features

- Rating to 1000V PRV
deal for printed circuit board
- Low forward voltage drop, high current capability
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- The plastic material has U/L flammability classification 94V-0

GBJ



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave ,60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

CHARACTERISTICS	SYMBOL	GBJ6AG	GBJ6BG	GBJ6DG	GBJ6G	GBJ6JG	GBJ6KG	GBJ6MG	UNIT
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward (with heatsink Note 2) Rectified Current @ T _c =100°C (without heatsink)	I _(AV)					6.0			A
						2.8			
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I _{FSM}					175			A
Maximum Forward Voltage at 3.0A DC	V _F					1.1			V
Maximum DC Reverse Current @ T _J =25°C at Rated DC Blocking Voltage @ T _J =125°C	I _R					10.0			µA
						500			
I ² t Rating for Fusing (t<8.3ms)	I ² t					120			A ² s
Typical Junction Capacitance Per Element (Note1)	C _J					55			pF
Typical Thermal Resistance	R _{θJC}					1.8			°C/W
Operating Temperature Range	T _J					-55 to +150			°C
Storage Temperature Range	T _{STG}					-55 to +150			°C

NOTES: 1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2. Device mounted on 75mm*75mm*1.6mm Cu plate heatsink.

FIG.1-FORWARD CURRENT DERATING CURVE

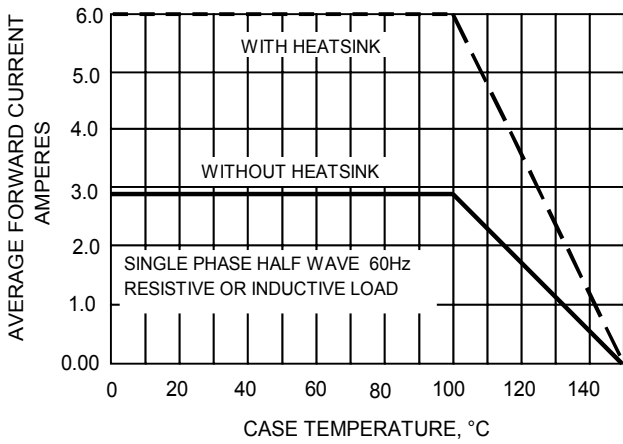


FIG.2-MAXIMUM NON-REPETITIVE SURGE CURRENT

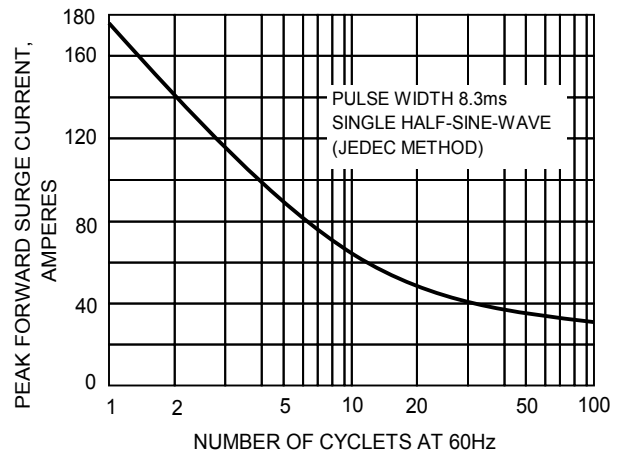


FIG.3-TYPICAL JUNCTION CAPACITANCE

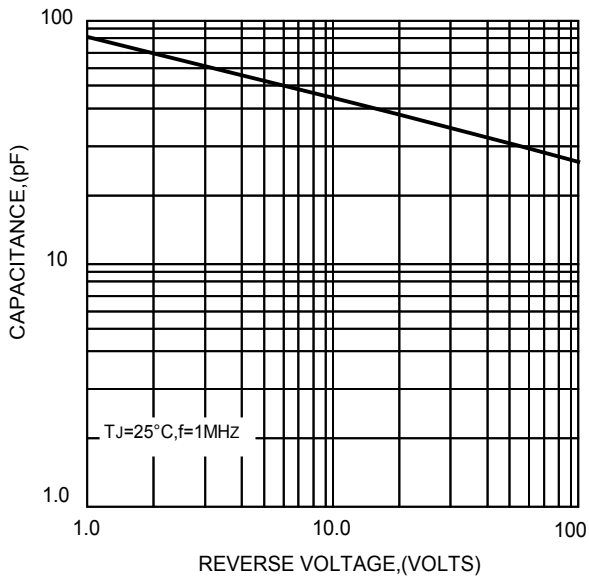


FIG.3-TYPICAL FORWARD CHARACTERISTICS

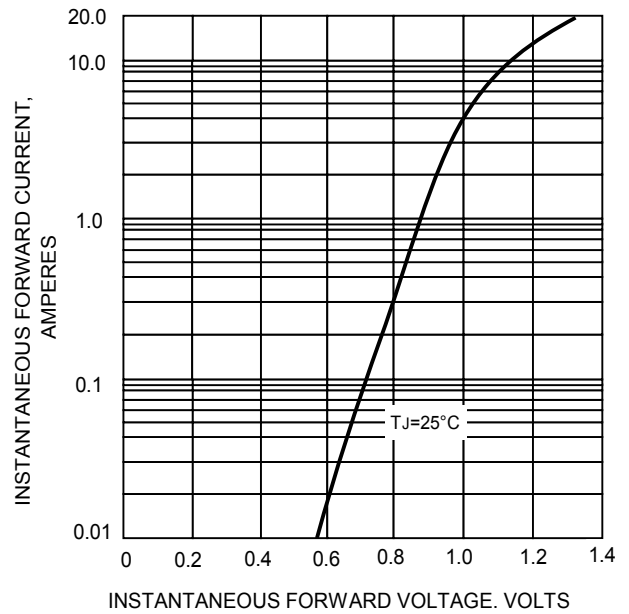


FIG.5-TYPICAL REVERSE CHARACTERISTICS

